

L Number	Hits	Search Text	DB	Time stamp
1	44	(sealant or filler) with thermoharden\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 11:03
2	55248	347/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 10:46
3	0	((sealant or filler) with thermoharden\$) and 347/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 10:46
4	803	thermoharden\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 10:46
5	21	347/\$.ccls. and thermoharden\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 10:51
6	144302	(ink or bubble) adj jet or inkjet or bubblejet	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 10:52
7	4302883	substrate or board or chip or head or printhead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 10:54
8	143	thermoharden\$ same (substrate or board or chip or head or printhead)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 10:54
9	10	(thermoharden\$ same (substrate or board or chip or head or printhead)) and ((ink or bubble) adj jet or inkjet or bubblejet)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 10:55
10	4	((thermoharden\$ same (substrate or board or chip or head or printhead)) and ((ink or bubble) adj jet or inkjet or bubblejet)) not (347/\$.ccls. and thermoharden\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 10:55
11	2	6471901.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 11:03
12	10	("4083902" "4962584" "5227812" "5576748" "5868887" "6000924" "6027590" "6041501" "6080354" "6109736").PN.	USPAT	2004/05/23 10:56
13	3	("5754205" "5861902" "5912684").PN.	USPAT	2004/05/23 10:56
14	149314	thermoset\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 11:03
15	10022	(sealant or filler) with thermoset\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 11:03

16	29	((sealant or filler) with thermoset\$) and 347/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 11:03
17	14	((sealant or filler) with thermoharden\$) same (substrate or board or chip or head or printhead)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 11:04
19	122	((sealant or filler) with thermoset\$) and ((ink or bubble) adj jet or inkjet or bubblejet)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 11:08
21	25	((sealant or filler) with thermoset\$) and ((ink or bubble) adj jet or inkjet or bubblejet)) and 347/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 11:19
22	2	6659591.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 11:18
23	3	("5360943" "5422667" "5459500").PN.	USPAT	2004/05/23 11:13
24	2252	cannon.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 11:18
25	3	cannon.in. and 347/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 11:18
26	845	cannon.as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 11:18
27	28159	fitzpatrick.att.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 11:20
28	4098	fitzpatrick.att. and 347/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 11:20
29	29908	(substrate or board or chip or head or printhead) same thermoset\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 11:22
30	59	(fitzpatrick.att. and 347/\$.ccls.) and ((substrate or board or chip or head or printhead) same thermoset\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 11:49
31	2936	(substrate or board or chip or head or printhead) same thermoset\$ same seal\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 11:24
32	0	"3128" and ((substrate or board or chip or head or printhead) same thermoset\$ same seal\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 11:24

33	5	(fitzpatrick.att. and 347/\$.ccls.) and ((substrate or board or chip or head or printhead) same thermoset\$ same seal\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 11:25
34	43	((substrate or board or chip or head or printhead) same thermoset\$ same seal\$) and 347/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 11:30
35	11508	epoxy same (substrate or board or chip or head or printhead) same seal\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 11:35
36	211	(epoxy same (substrate or board or chip or head or printhead) same seal\$) and 347/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 11:34
37	5123	epoxy with (substrate or board or chip or head or printhead) with seal\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 11:36
38	102	(epoxy with (substrate or board or chip or head or printhead) with seal\$) and 347/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 11:37
39	1	"09/986,808"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 11:50
-	18	US-625770B1-\$.DID. OR US-624134B1-\$.DID. OR US-5227812-\$.DID. OR US-5576748-\$.DID. OR US-4083902-\$.DID. OR US-4962584-\$.DID. OR US-5868887-\$.DID. OR US-6000924-\$.DID. OR US-6027590-\$.DID. OR US-6041501-\$.DID. OR US-6080354-\$.DID. OR US-6109736-\$.DID.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/23 10:45